



#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

| V <sub>(BR)DSS</sub> | R <sub>DS(on)max</sub>         | I <sub>D</sub><br>T <sub>A</sub> = 25°C |
|----------------------|--------------------------------|-----------------------------------------|
| -20V                 | 16mΩ @ V <sub>GS</sub> = -4.5V | -12.8A                                  |
| -2UV                 | 25mΩ @ V <sub>GS</sub> = -2.0V | -10A                                    |

## **Description and Applications**

This new generation MOSFET has been designed to minimize the onstate resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power management functions
- Notebook PC Applications
- Portable Equipment Applications

### **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Low Input/Output Leakage
- ESD Protected Gate up to 2kV
- Lead Free by Design, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

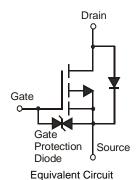
- Case: U-DFN2523-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)



Pin 1, 2 = Source Pin 3 = Gate Pin 4, 5, 6 = Drain



Bottom View



#### Ordering Information (Note 3)

| Part Number   | Case        | Packaging            |
|---------------|-------------|----------------------|
| DMP2018LFK-7  | U-DFN2523-6 | 3,000 / Tape & Reel  |
| DMP2018LFK-13 | U-DFN2523-6 | 10,000 / Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



P8 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: Y = 2011) M = Month (ex: 9 = September)

Date Code Key

| Year  | 201 | 1   | 2012 |     | 2013 | 20  | 14  | 2015 |     | 2016 |     | 2017 |
|-------|-----|-----|------|-----|------|-----|-----|------|-----|------|-----|------|
| Code  | Υ   |     | Z    |     | Α    |     | 3   | С    |     | D    |     | Е    |
| Month | Jan | Feb | Mar  | Apr | May  | Jun | Jul | Aug  | Sep | Oct  | Nov | Dec  |
| Code  | 1   | 2   | 3    | 1   | 5    | 6   | 7   | Ω    | ٥   | 0    | N   | D    |



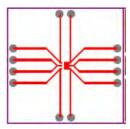
# 

| Characteristic                                            |                 | Symbol                         | Value          | Units          |   |
|-----------------------------------------------------------|-----------------|--------------------------------|----------------|----------------|---|
| Drain-Source Voltage                                      |                 | $V_{DSS}$                      | -20            | V              |   |
| Gate-Source Voltage                                       |                 |                                | $V_{GSS}$      | ±12            | V |
| Continuous Prain Correct (Note 5) V                       | Steady<br>State | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | -9.2<br>-7.3   | А |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V | t<5s            | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | -12.8<br>-10.3 | А |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = -2.0V | Steady<br>State | $T_A = 25$ °C<br>$T_A = 70$ °C | l <sub>D</sub> | -7.1<br>-6     | А |
| Continuous Diain Curient (Note 5) VGS = -2.0V             | t<5s            | $T_A = 25$ °C<br>$T_A = 70$ °C | I <sub>D</sub> | -10<br>-8.3    | А |
| Maximum Continuous Body Diode Forward Current             | (Note 5)        | Is                             | -3             | Α              |   |
| Pulsed Drain Current (10μs pulse, duty cycle = 1%)        | )               | $I_{DM}$                       | -90            | Α              |   |
| Avalanche Current (Note 6)                                | I <sub>AS</sub> | 17                             | A              |                |   |
| Repetitive Avalanche Energy (Note 6)                      |                 | E <sub>AS</sub>                | 72             | mJ             |   |

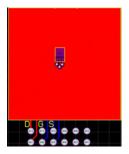
## **Thermal Characteristics**

| Characteristic                                   |               | Symbol           | Value      | Units |
|--------------------------------------------------|---------------|------------------|------------|-------|
| Total Power Dissipation (Note 4)                 | $T_A = 25$ °C | c d              | 1          | W     |
| Total Power Dissipation (Note 4)                 | $T_A = 70$ °C | P <sub>D</sub>   | 0.63       | VV    |
| Thermal Resistance, Junction to Ambient (Note 4) | Steady State  |                  | 126        | °C/W  |
| Thermal Resistance, Junction to Ambient (Note 4) | t<5s          | $R_{\theta JA}$  | 60         | C/VV  |
| Total Power Dissipation (Note 5)                 | $T_A = 25$ °C | Pn               | 2.1        | W     |
| Total Fower Dissipation (Note 3)                 | $T_A = 70$ °C | FD               | 1.3        | V V   |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State  | 2                | 61         |       |
| Thermal Resistance, Junction to Ambient (Note 5) | t<5s          | $R_{	heta JA}$   | 29         | °C/W  |
| Thermal Resistance, Junction to Case             | ·             | $R_{	heta JC}$   | 6.4        |       |
| Operating and Storage Temperature Range          |               | $T_{J_i}T_{STG}$ | -55 to 150 | °C    |

Notes: 4. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.



Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate



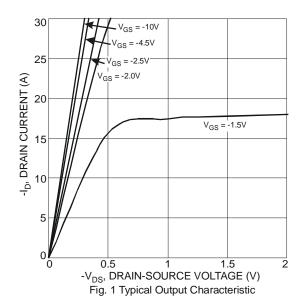


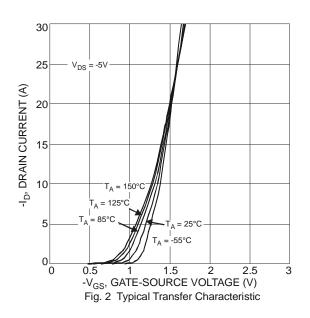
# Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise stated

| Characteristic                                        | Symbol               | Min   | Тур   | Max  | Unit      | Test Condition                                |  |
|-------------------------------------------------------|----------------------|-------|-------|------|-----------|-----------------------------------------------|--|
| OFF CHARACTERISTICS (Note 7)                          |                      |       |       |      |           |                                               |  |
| Drain-Source Breakdown Voltage                        | BV <sub>DSS</sub>    | -20   | -     | 1    | <b>V</b>  | $V_{GS} = 0V, I_D = -10mA$                    |  |
| Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C | I <sub>DSS</sub>     | -     | -     | -1   | μΑ        | $V_{DS} = -20V, V_{GS} = 0V$                  |  |
| Gate-Source Leakage                                   | I <sub>GSS</sub>     | -     | -     | ±2   | μΑ        | $V_{GS} = \pm 10V, V_{DS} = 0V$               |  |
| ON CHARACTERISTICS (Note 7)                           |                      |       |       |      |           |                                               |  |
| Gate Threshold Voltage                                | V <sub>GS(th)</sub>  | -0.45 | -     | -1.2 | V         | $V_{DS} = -10V, I_{D} = -200\mu A$            |  |
|                                                       |                      | -     | 10    | 16   |           | $V_{GS} = -4.5V$ , $I_{D} = -3.6A$            |  |
| Static Drain-Source On-Resistance                     | В                    | -     | 12    | 20   | $m\Omega$ | $V_{GS} = -2.5V$ , $I_D = -3.6A$              |  |
| Static Dialii-Source Off-Resistance                   | R <sub>DS (ON)</sub> | -     | 13.6  | 25   | 11122     | $V_{GS} = -2.0V, I_D = -1.8A$                 |  |
|                                                       |                      | -     | 20    | -    |           | V <sub>GS</sub> = -1.5V, I <sub>D</sub> = -1A |  |
| Forward Transfer Admittance                           | Y <sub>fs</sub>      | 10    | 17    | -    | S         | $V_{DS} = -10V, I_D = -3.6A$                  |  |
| Diode Forward Voltage                                 | V <sub>SD</sub>      | -     | 0.7   | 1.2  | V         | V <sub>GS</sub> = 0V, I <sub>S</sub> = -3.6A  |  |
| DYNAMIC CHARACTERISTICS (Note 8)                      |                      |       |       |      |           |                                               |  |
| Input Capacitance                                     | C <sub>iss</sub>     | -     | 4748  | -    |           | 10)/ )/ 0)/                                   |  |
| Output Capacitance                                    | Coss                 | -     | 833   | -    | pF        | $V_{DS} = -10V, V_{GS} = 0V,$<br>f = 1.0MHz   |  |
| Reverse Transfer Capacitance                          | C <sub>rss</sub>     | -     | 339   | -    |           | I = 1.0IVIH2                                  |  |
| Gate Resistance                                       | Rg                   | -     | 6.2   | -    | Ω         | $V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$    |  |
| Total Gate Charge (V <sub>GS</sub> = -10V)            | Qg                   | -     | 113   | -    |           |                                               |  |
| Total Gate Charge (V <sub>GS</sub> = -4.5V)           | Qg                   | -     | 53    | -    | 0         | 10/1 704                                      |  |
| Gate-Source Charge                                    | Q <sub>qs</sub>      | -     | 7.1   | -    | nC        | $V_{DS} = -16V, I_{D} = -7.2A$                |  |
| Gate-Drain Charge                                     | $Q_{qd}$             | -     | 8.5   | -    |           |                                               |  |
| Turn-On Delay Time                                    | t <sub>D(on)</sub>   | -     | 22.8  | -    |           |                                               |  |
| Turn-On Rise Time                                     | tr                   | -     | 29.8  | -    |           | $V_{DD} = -10V, V_{GS} = -4.5V,$              |  |
| Turn-Off Delay Time                                   | t <sub>D(off)</sub>  | -     | 240.8 | -    | ns        | $R_G = 4.7\Omega$ , $I_D = -3.6A$             |  |
| Turn-Off Fall Time                                    | t <sub>f</sub>       | -     | 100.6 | 1    |           |                                               |  |

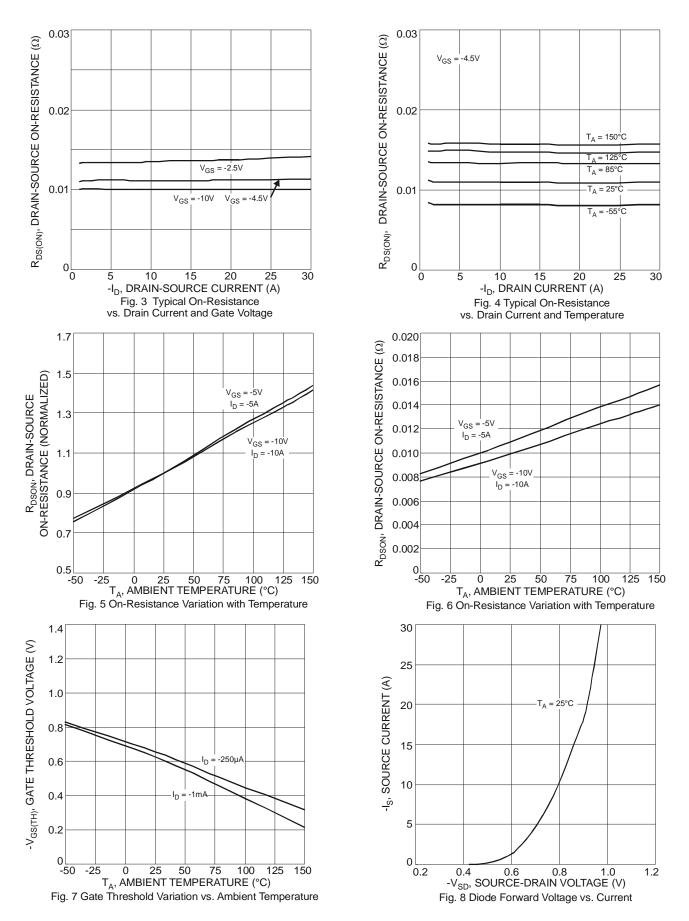
Notes:

- UIS in production with L = 0.5mH, TJ = 25°C
   Short duration pulse test used to minimize self-heating effect.
   Guaranteed by design. Not subject to production testing.

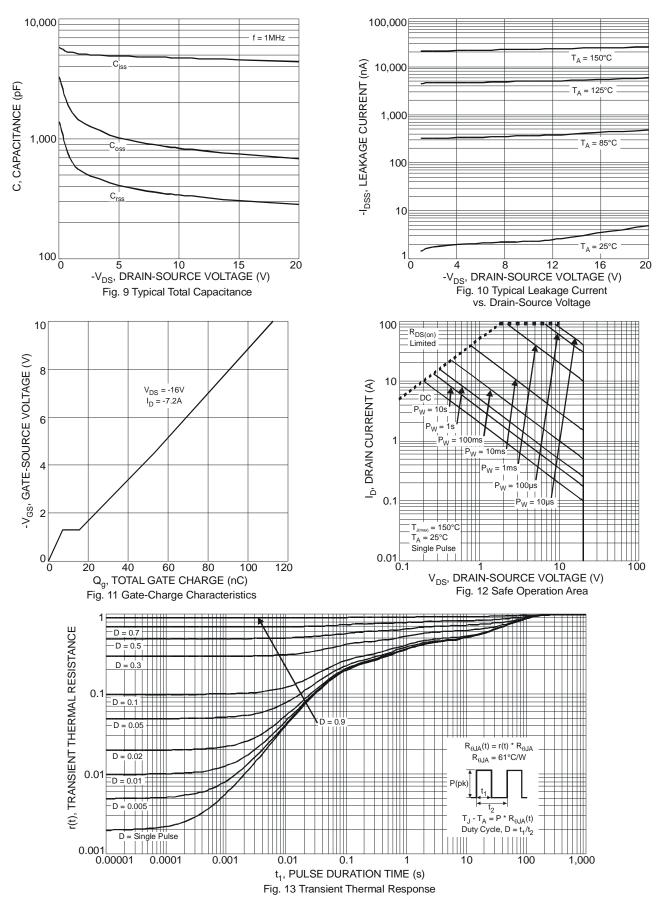






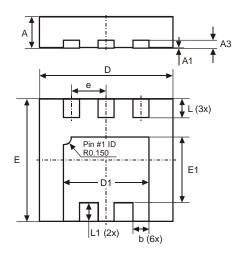






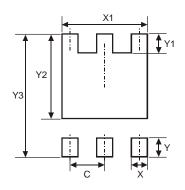


# **Package Outline Dimensions**



| U-DFN2523-6          |      |      |       |  |  |  |  |
|----------------------|------|------|-------|--|--|--|--|
| Dim                  | Min  | Max  | Тур   |  |  |  |  |
| Α                    | 0.57 | 0.63 | 0.60  |  |  |  |  |
| A1                   | 0    | 0.05 | 0.02  |  |  |  |  |
| А3                   | 1    | _    | 0.152 |  |  |  |  |
| b                    | 0.25 | 0.35 | 0.30  |  |  |  |  |
| D                    | 2.45 | 2.55 | 2.50  |  |  |  |  |
| D1                   | 1.55 | 1.65 | 1.60  |  |  |  |  |
| е                    | _    | _    | 0.65  |  |  |  |  |
| Е                    | 2.25 | 2.35 | 2.30  |  |  |  |  |
| E1                   | 1.18 | 1.28 | 1.23  |  |  |  |  |
| L                    | 0.30 | 0.40 | 0.35  |  |  |  |  |
| L1                   | 0.30 | 0.40 | 0.35  |  |  |  |  |
| All Dimensions in mm |      |      |       |  |  |  |  |

# **Suggested Pad Layout**



| Dimensions | Value (in mm) |
|------------|---------------|
| С          | 0.650         |
| Х          | 0.400         |
| X1         | 1.700         |
| Υ          | 0.650         |
| Y1         | 0.450         |
| Y2         | 1.830         |
| Y3         | 2.700         |



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